

SOT1937-1
SIL3, plastic, DIL-bent-SIL package; 3 terminals; 2.54 mm pitch; 14.32 mm x 9.96 mm x 2.50 mm body

10 April 2019

Package inform

Package information

Package summary 1

Terminal position code P (perpendicular)

SIL3 Package type descriptive code

Package style descriptive code DBS (DIL-bent-SIL)

Package body material type P (plastic)

Mounting method type T (through-hole mount)

Issue date 13-02-2019 98ASA01106D Manufacturer package code

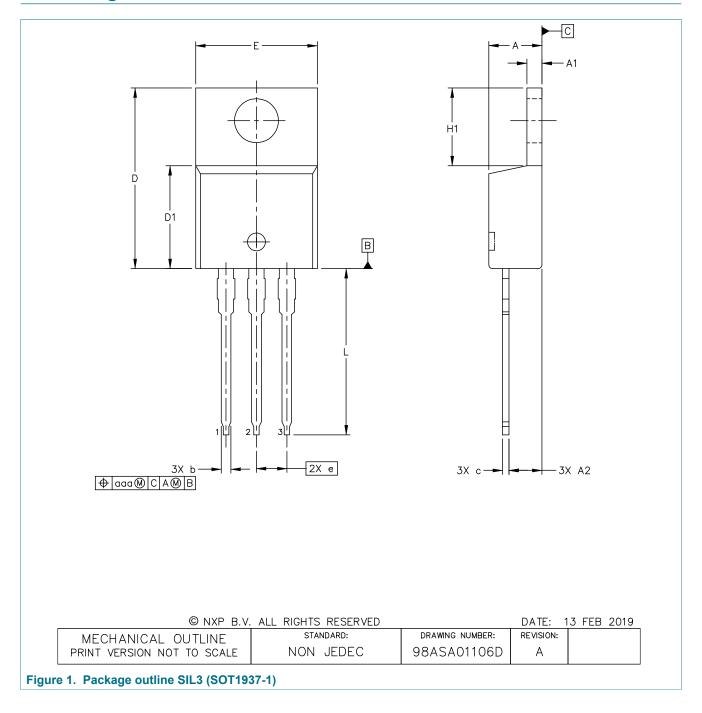
Table 1. Package summary

| Parameter | Min | Nom | Max | Unit |
|--------------------------------|-----|-------|-----|------|
| package length | - | 14.32 | - | mm |
| package width | - | 9.96 | - | mm |
| package height | - | 2.5 | - | mm |
| actual quantity of termination | - | 3 | - | |

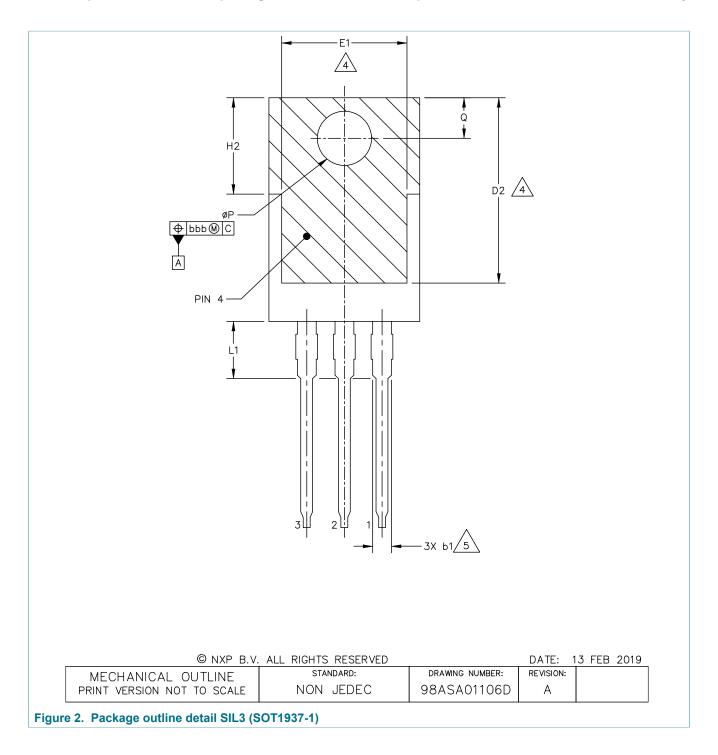


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2 Package outline



SIL3, plastic, DIL-bent-SIL package; 3 terminals; 2.54 mm pitch; 14.32 mm x 9.96 mm x 2.50 mm body



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NOTES:

- 1. CONTROLLING DIMENSION: MILLIMETER, ANGLES ARE IN DEGREES.
- 2. INTERPRET DIMENSIONS AND TOLERANCES AS PER ASME Y14.5M-1994.
- 3. DIMENSION D AND E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.13 MM (.005 INCH) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY.
- HATCHING REPRESENTS THE EXPOSED AREA OF THE THERMAL PAD (PIN 4). DIMENSIONS D2 AND E1 REPRESENT THE VALUES BETWEEN THE TWO OPPOSITE POINTS ALONG THE EDGES OF THE EXPOSED AREA OF THE THERMAL PAD. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSION D1 AND E1.
- 6. EJECTOR MARKS ON TOP SURFACE ARE PERMITTED AND IT IS SUPPLIER OPTION. THE MAXIMUM DEPTH OF EJECTOR MARK IS 0.25 MM (.010 INCH)

| | INCH | | MILLIMETER | | | INCH | | MILLIMETER | |
|-----|------|------|------------|-------|-----|-----------|------|------------|-------|
| DIM | MIN | MAX | MIN | MAX | DIM | MIN | MAX | MIN | MAX |
| Α | .167 | .190 | 4.25 | 4.83 | E1 | .303 | | 7.70 | |
| A1 | .047 | .053 | 1.20 | 1.34 | е | .10 BSC | | 2.54 BSC | |
| A2 | .098 | .115 | 2.50 | 2.92 | H1 | .240 | .264 | 6.10 | 6.70 |
| b | .028 | .038 | 0.71 | 0.97 | H2 | .240 | .264 | 6.10 | 6.70 |
| b1 | .045 | .070 | 1.14 | 1.78 | L | .500 | .567 | 12.70 | 14.40 |
| С | .014 | .024 | 0.356 | 0.61 | L1 | .144 | .159 | 3.65 | 4.05 |
| D | .564 | .624 | 14.32 | 15.86 | Р | .142 | .155 | 3.60 | 3.95 |
| D1 | .330 | | 8.39 | | Q | .100 | .119 | 2.54 | 3.04 |
| D2 | .480 | .504 | 12.20 | 12.80 | aaa | .014 | | 0.35 | |
| E | .392 | .412 | 9.96 | 10.47 | bbb | .014 0.35 | | 35 | |
| | | | | | | | | | |

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|----------------------------|---------------------|-----------------|-----------|------------|
| MECHANICAL OUTLINE | STANDARD: | DRAWING NUMBER: | REVISION: | |
| PRINT VERSION NOT TO SCALE | NON JEDEC | 98ASA01106D | Α | |

Figure 3. Package outline note SIL3 (SOT1937-1)

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3 Legal information

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